



Click [here](#) for the 3D model.

Dimensions

Case Code	40
L	7.9mm +/-0.38mm
W	12.2mm +/-0.4mm
H	8.9mm +/-0.38mm
S	1.4mm +/-0.38mm
F	10.5mm +/-0.4mm
K	6.6mm +/-0.38mm

Packaging Specifications

Packaging	T&R, 178mm
-----------	------------

General Information

Series	TSP
Dielectric	Polymer Tantalum
Style	Stacked Chip
Description	SMD, Polymer, KO, Stacks, High Reliability
Features	High Reliability
RoHS	Yes
Termination	Tin
Termination (Stack)	Solder Coated
AEC-Q200	No

Specifications

Capacitance	600 uF
Capacitance Tolerance	20%
Voltage DC	25 VDC (105C), 16.75 VDC (125C)
Temperature Range	-55/+125°C
Rated Temperature	105°C
Dissipation Factor	10% 120Hz 25C
Failure Rate	N/A
Resistance	15 mOhms (100kHz 25C)
Leakage Current	1500 uA (5min 25°C)